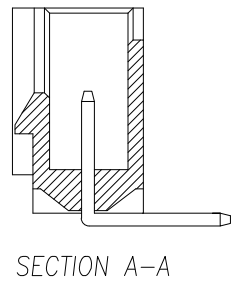
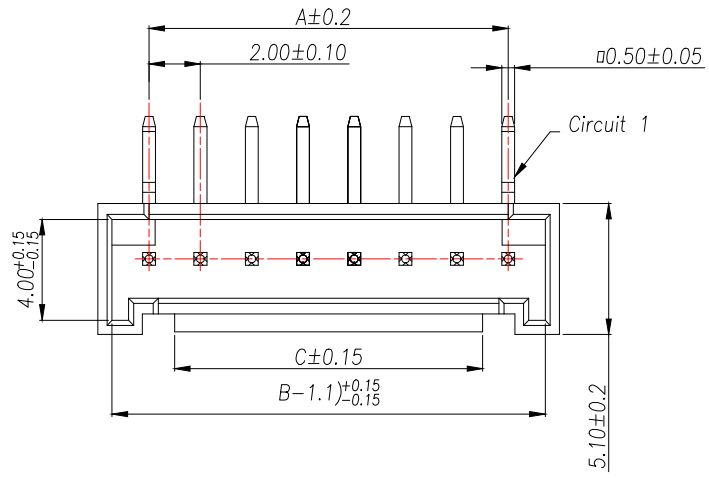


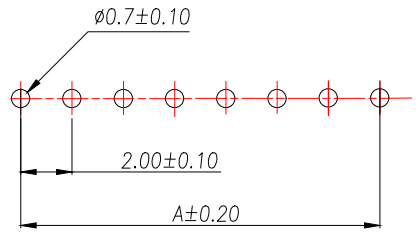
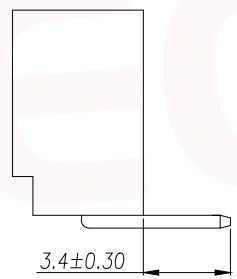
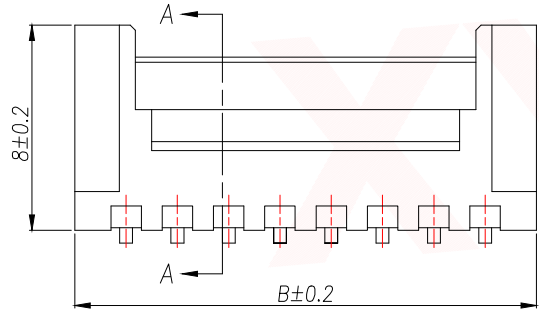
REV.	Q'TY	ECN. NO.	APR.	DATE

PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE

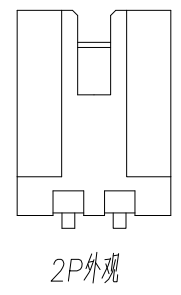


- 技术要求:
- 1、塑件材料:PA66
 - 2、接触件:黄铜镀锡
 - 3、接触电阻: ≤10mΩ
 - 4、绝缘电阻: ≥1000MΩ
 - 5、额定电压:250V AC DC
 - 6、额定电流:2.0A AC DC
 - 7、耐压:能承受1000V AC/Min ute
 - 8、工作温度: -25°~+85°
 - 9、可焊性试验:浸锡面积≥95%温度220±5°,时间 2.5±0.5秒
 - 10、铅和镉等六大有害物质含量要符合环保要求

Part No	PIN	A	B	C
XY-HY2.0-2A21	2	2	6	
XY-HY2.0-3A21	3	4	8	2
XY-HY2.0-4A21	4	6	10	4
XY-HY2.0-5A21	5	8	12	6
XY-HY2.0-6A21	6	10	14	8
XY-HY2.0-7A21	7	12	16	10
XY-HY2.0-8A21	8	14	18	12
XY-HY2.0-9A21	9	16	20	14
XY-HY2.0-10A21	10	18	22	16
XY-HY2.0-11A21	11	20	24	18
XY-HY2.0-12A21	12	22	26	20
XY-HY2.0-13A21	13	24	28	22
XY-HY2.0-14A21	14	26	30	24
XY-HY2.0-15A21	15	28	32	26



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)



2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN,再镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	本色
序号	名称	材料	数量	备注

厦门市辛译精密电子有限公司
Xiamen XinYi Xyconn Electronics Co.,Ltd

DIMENSION IN mm		TOLERANCE UNLESS OTHERWISE SPECIFIED		APR. Alex CHK. Jack DRA. Can TITLE: WAFER 2.0mm H8.0mm 90° DIP DWG NO. XY-HY2.0-NA21 PROJ. CUSTOMER DRAWING SIZE A4 SCALE 1:1 SHEET 1/1 REV. A	
.X±0.35	X.*± 5°				
.XX±0.25	.X.*± 3°				
.XXX±0.15	.XX.*± 1°				